**Precision Dicing Saw**

**Precision Dicing and Cutting Saw *******

Based on precision CNC milling machine design, this saw can be used for dicing or cutting all kinds of materials up to 4” diameter wafers or 8” in length x 4” width, and 1” thick components.

**FEATURES**

- 1/2 HP high torque DC motor with variable speed up to 3000 rpm
- Power input 110 to 240 VAC
- X,Y and Z three dimensions linear motion up to X= 8”, Y=4” and Z = 4”
- CNC controlled step motor with 0.0025 mm moving resolution and 0.01 mm position accuracy
- User friendly software allow you cutting or dicing automatically via Windows based PC
- A precision 100 mm dia. sample stage with two angle adjustable in 360° rotating, and 15° tilting, as well as a small vise, are ready for cutting material in a desired orientation
- One 4” dia x 0.3 mm thick sintered diamond wheel
- Two sets of flanges with 90 mm dia. (for dicing) and 40 mm dia (for deep cutting)
- Assemblies of Water jetting, draining, splashing protection Include

**Standard Package**

- A cutting machines with a spindle motor and three step motors
- Three-axis step motor drive with cables (Computer not included)
- One set of sample holding materials (1ea)
  - 4"dia x 1/4” thick glass plate
  - 2" x 2" x 0.5” graphite plate
  - 2" x 0.5” x 1/16” Aluminum plate, and
  - crystal wax
- Base dimension of 400 x 400mm
- Shipping weight 150 lbs (68Kgs)

**Optional Accessories**

- 4” dia. vacuum chuck for wafer holding
- Adhesive film for wafer dicing without wax
- Immersion water pump for coolant circulating without tap water
- Sintered diamond blade (3” x 0.2 mm or 4” x 0.3 mm)